

PMEG10020ELXD

100 V, 2 A low leakage current Schottky barrier rectifier
7 October 2025 Product data sheet

1. General description

Planar Schottky barrier rectifier encapsulated in a CFP2-HP (SOD323HP) power flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Low leakage current
- · High surge current robustness
- High power capability due to clip-bond package
- Power flat lead plastic package with exposed heatsink for optimal thermal connection

3. Applications

- High efficiency applications
- Switch mode power supply
- · Freewheeling application
- · Reverse polarity protection
- OR-ing

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 164 °C		-	-	2	A
V _R	reverse voltage	T _j = 25 °C		-	-	100	V
V _F	forward voltage	I _F = 2 A; pulsed; T _j = 25 °C	[1]	-	810	875	mV
I_R	reverse current	$V_R = 100 \text{ V}$; pulsed; $T_j = 25 \text{ °C}$	[1]	-	0.25	2	μΑ
		$V_R = 100 \text{ V}$; pulsed; $T_j = 125 \text{ °C}$	[1]	-	0.35	2.8	mA

[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	, Th	
2	А	anode	Transparent top view CFP2-HP (SOD323HP)	K -∏ - A sym001

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG10020ELXD	CFP2-HP	SOD323HP: plastic surface-mounted package with solderable lead ends; 2.2 mm x 1.3 mm x 0.68 mm body	SOD323HP

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG10020ELXD	AJ

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _R	reverse voltage	T _j = 25 °C		-	100	V
I _F	forward current	δ = 1; $T_{sp} \le 162 ^{\circ}\text{C}$		-	2.8	А
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 164 °C		-	2	A
I _{FSM}	non-repetitive peak forward current	$t_p = 8.3 \text{ ms}$; half sine wave; $T_{j(init)} = 25 \text{ °C}$		-	25	A
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	0.65	W
			[2]	-	1.2	W
Tj	junction temperature			-	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

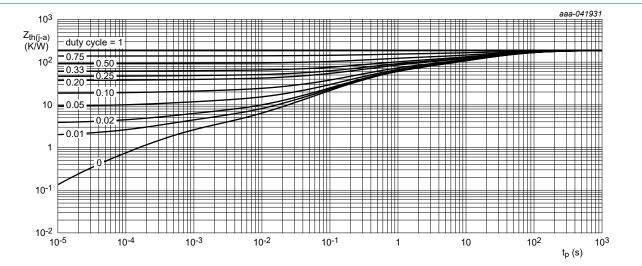
^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

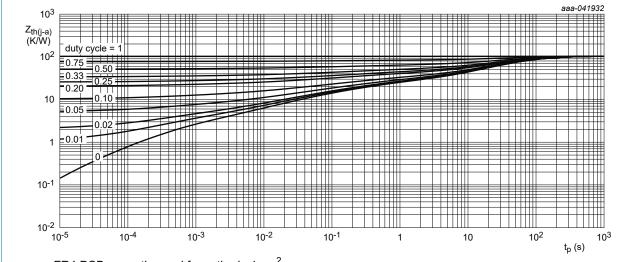
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R _{th(j-a)}	thermal resistance from	in free air	[1] [2]	-	-	230	K/W
junction	junction to ambient	tion to ambient	[1] [3]	-	-	125	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	6	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

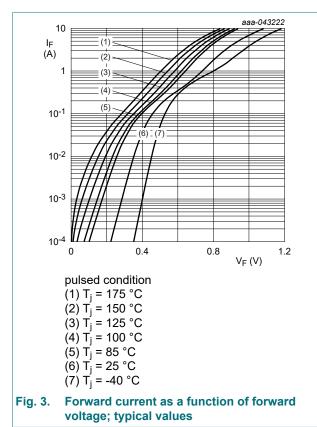
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	I_R = 1 mA; pulsed; T_j = 25 °C	[1]	100	-	-	V
V _F	forward voltage	I _F = 1 A; pulsed; T _j = 25 °C	[1]	-	735	810	mV
		I _F = 2 A; pulsed; T _j = 25 °C	[1]	-	810	875	mV
		I _F = 2 A; pulsed; T _j = -40 °C	[1]	-	910	990	mV
		I _F = 2 A; pulsed; T _j = 125 °C	[1]	-	650	730	mV
I _R	reverse current	V _R = 100 V; pulsed; T _j = 25 °C	[1]	-	0.25	2	μΑ
		V _R = 100 V; pulsed; T _j = 125 °C	[1]	-	0.35	2.8	mA
C _d	diode capacitance	V _R = 4 V; f = 1 MHz; T _j = 25 °C		-	29	-	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C		-	19	-	pF
t _{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}$; $I_R = 1 \text{ A}$; $I_{R(meas)} = 0.25 \text{ A}$; $I_{j} = 25 \text{ °C}$		-	2.3	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 100 \text{ A/}\mu\text{s}; I_F = 1 \text{ A}; V_R = 30 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	8	-	ns
I _{RM}	peak reverse recovery current			-	0.34	-	Α
Q _{rr}	reverse recovery charge			-	1.6	-	nC
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	650	-	mV

[1] Very short pulse, in order to maintain a stable junction temperature.



aaa-043223 10⁻² I_R (A) (1) (2) 10-3 (3) 10-4 (5) 10⁻⁵ 10⁻⁶ (6) 10⁻⁷ 10-8 20 40 60 V_R (V) 0 pulsed condition (1) $T_i = 175 \,^{\circ}C$ (2) $T_j = 150 \,^{\circ}\text{C}$ (3) $T_j = 125 \,^{\circ}\text{C}$ (4) $T_i = 100 °C$ $(5) T_i = 85 °C$ (6) $T_i = 25 \,^{\circ}\text{C}$ Fig. 4. Reverse current as a function of reverse

voltage; typical values

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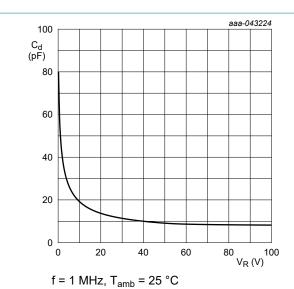
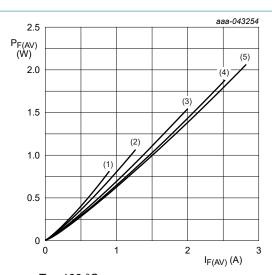
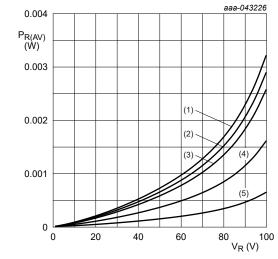


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



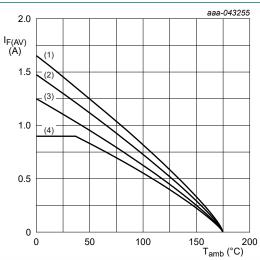
 $T_j = 100 \,^{\circ}\text{C}$ $(1) \, \delta = 0.1$ $(2) \, \delta = 0.2$ $(3) \, \delta = 0.5$ $(4) \, \delta = 0.8$ $(5) \, \delta = 1 \, (DC)$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 100 \text{ °C}$ $(1) \delta = 1 \text{ (DC)}$ $(2) \delta = 0.9$ $(3) \delta = 0.8$ $(4) \delta = 0.5$ $(5) \delta = 0.2$

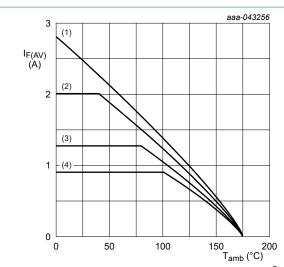
Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

 $T_j = 175$ °C (1) $\delta = 1$ (DC) (2) $\delta = 0.5$; f = 20 kHz (3) $\delta = 0.2$; f = 20 kHz (4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

 $T_i = 175 \,{}^{\circ}\text{C}$

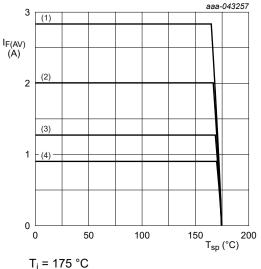
 $(1) \delta = 1 (DC)$

 $(2) \delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

 $(4) \delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values

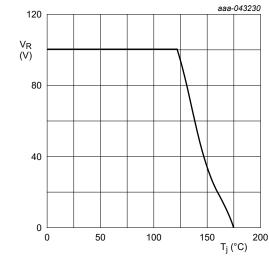


 $(1) \delta = 1 (DC)$

(2) $\delta = 0.5$; f = 20 kHz(3) $\delta = 0.2$; f = 20 kHz

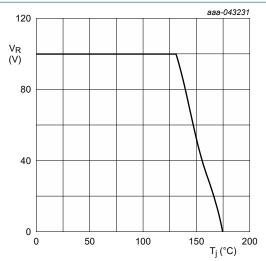
 $(4) \delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values



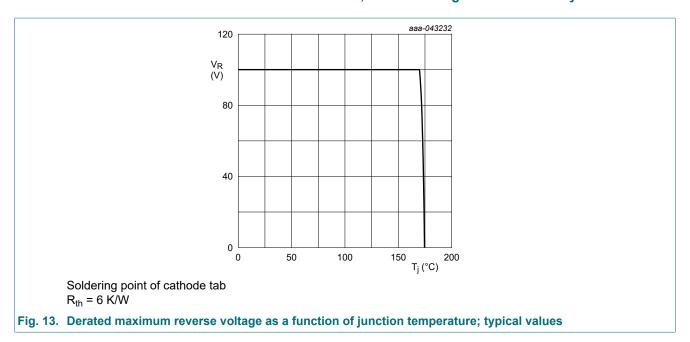
FR4 PCB, standard footprint $R_{th} = 230 \text{ K/W}$

of junction temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm² $R_{th} = 125 \text{ K/W}$

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



11. Test information

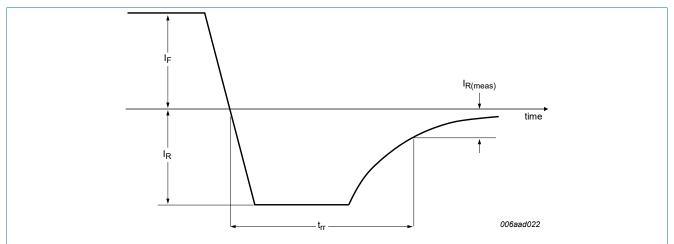


Fig. 14. Reverse recovery definition; step recovery

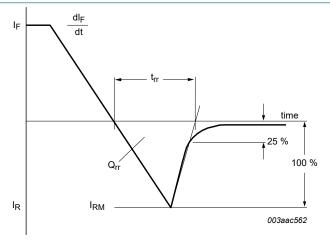


Fig. 15. Reverse recovery definition; ramp recovery

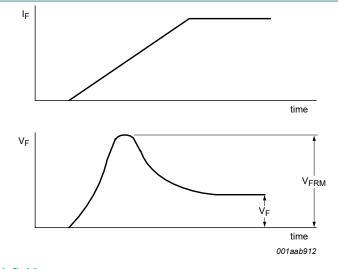
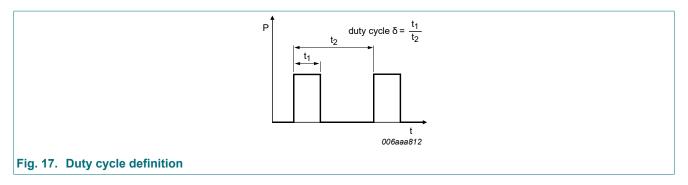


Fig. 16. Forward recovery definition



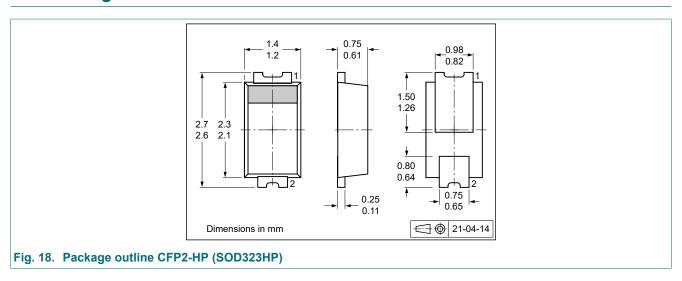
The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

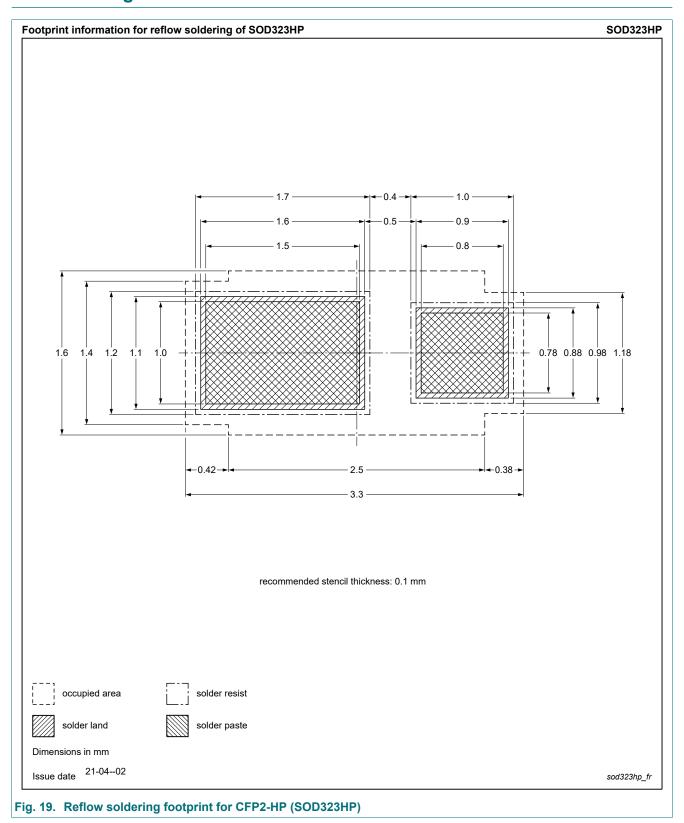
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_{M} \times \sqrt{\delta}$

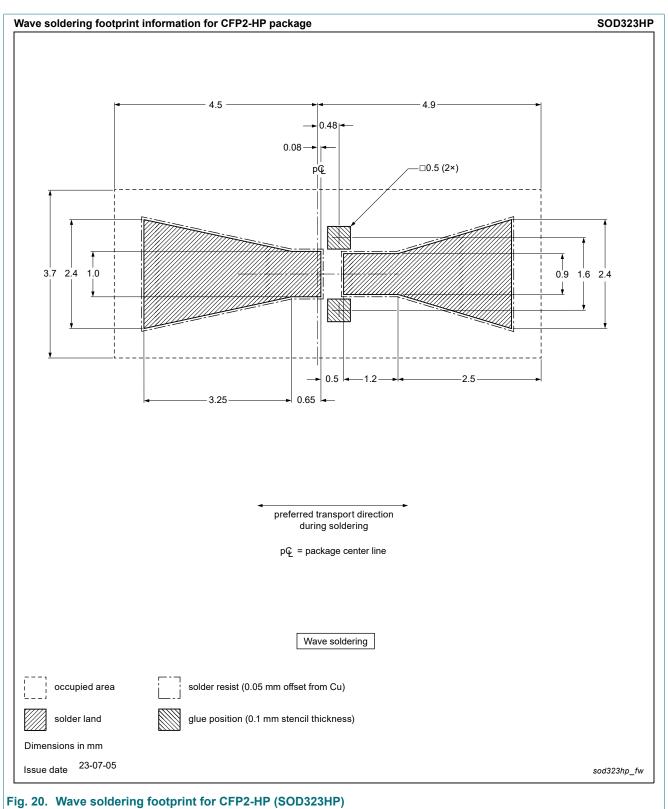
with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

12. Package outline



13. Soldering





14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG10020ELXD v.1	20251007	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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